

6-line IPAD™, EMI filter including ESD protection

Features

- 6-line low-pass-filter
- High efficiency in EMI filtering
- Very low PCB space occupation: < 4.4 mm²
- Lead-free package
- Very thin package: 0.65 mm
- High efficiency in ESD suppression
- High reliability offered by monolithic integration
- High reducing of parasitic elements through integration and wafer level packaging

Complies with the following standards

- IEC 61000-4-2 level 4 on external pins
 - 15 kV (air discharge)
 - 8 kV (contact discharge)
- MIL STD 883E - Method 3015-6 Class 3

Applications

- High speed MultiMediaCard

Description

The EMIF06-HMC01F2 is a highly integrated array designed to suppress EMI / RFI noise for high speed MultiMediaCard port filtering. The EMIF06-HMC01F2 Flip Chip packaging means the package size is equal to the die size.

Additionally, this filter includes ESD protection circuitry which prevents damage to the application when subjected to ESD surges up to 15 kV.

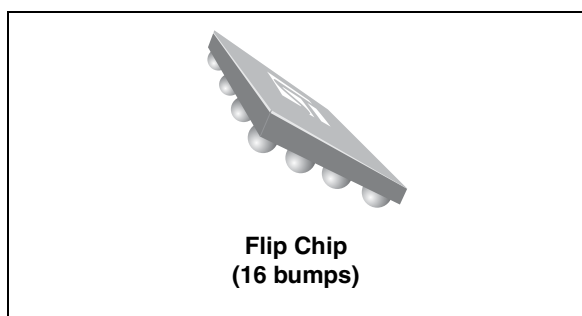


Figure 1. Pin layout (bump side)

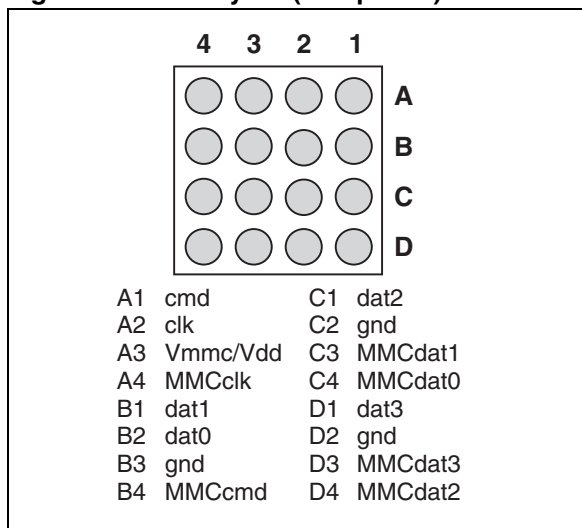
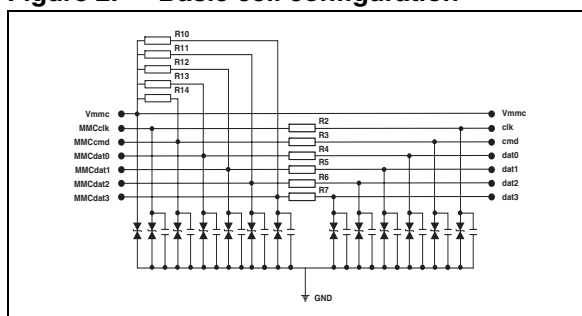


Figure 2. Basic cell configuration



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1 Characteristics

Table 1. Absolute maximum ratings ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

Symbol	Parameter and test conditions	Value	Unit
V_{PP}	Internal pins (A4, B4, C3, C4, D3, D4):		
	ESD discharge IEC61000-4-2, air discharge	2	kV
	ESD discharge IEC61000-4-2, contact discharge	2	
	External pins (A1, A2, A3, B1, B2, C1, D1):		
ESD discharge IEC61000-4-2, air discharge	15		
	ESD discharge IEC61000-4-2, contact discharge	8	
T_j	Maximum junction temperature	125	$^{\circ}\text{C}$
T_{op}	Operating temperature range	-40 to +85	$^{\circ}\text{C}$
T_{stg}	Storage temperature range	-55 to 150	$^{\circ}\text{C}$

Table 2. Electrical characteristics ($T_{amb} = 25\text{ }^{\circ}\text{C}$)

Symbol	Parameters					
V_{BR}	Breakdown voltage					
I_{RM}	Leakage current @ V_{RM}					
V_{RM}	Stand-off voltage					
C_{line}	Input capacitance per line					
Symbol	Test conditions	Tolernace	Min	Typ	Max	Unit
V_{BR}	$I_R = 1\text{ mA}$		14			V
I_{RM}	$V_{RM} = 3\text{ V}$				0.1	μA
C_{line}	@ 0V				20	pF
$R_2, R_3, R_4, R_5, R_6, R_7$	$I = 50\text{ mA}$	$\pm 20\%$		50		Ω
$R_{10}, R_{11}, R_{12}, R_{13}$	$I = 50\text{ }\mu\text{A}$	$\pm 30\%$		75		k Ω
R_{14}	$I = 200\text{ }\mu\text{A}$	$\pm 30\%$		7		k Ω

Figure 3. S21 (dB) attenuation measurement

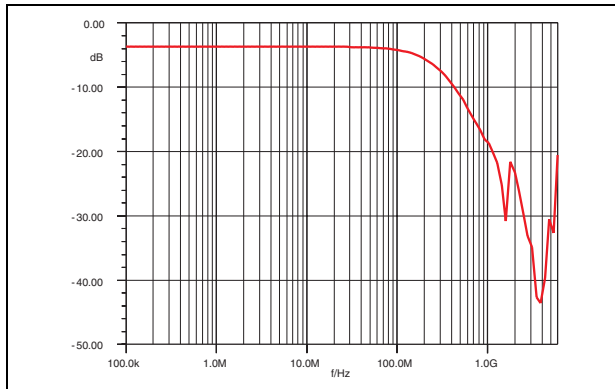


Figure 4. Analog crosstalk measurement

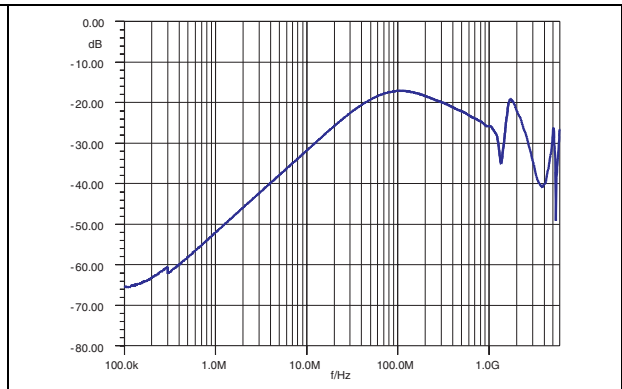


Figure 5. ESD response to IEC 61000-4-2 (+15kV air discharge) on one input (V_{in}) and on one output (V_{out})

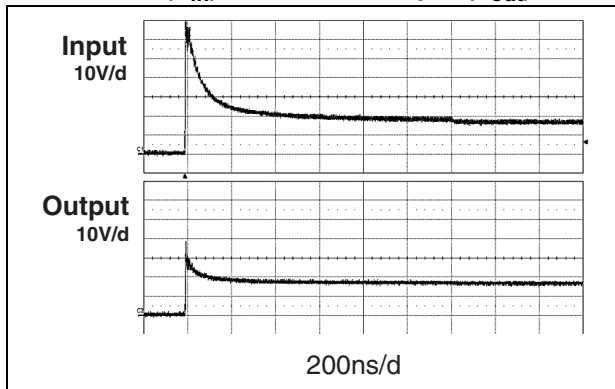


Figure 6. ESD response to IEC 61000-4-2 (-15kV air discharge) on one input (V_{in}) and on one output (V_{out})

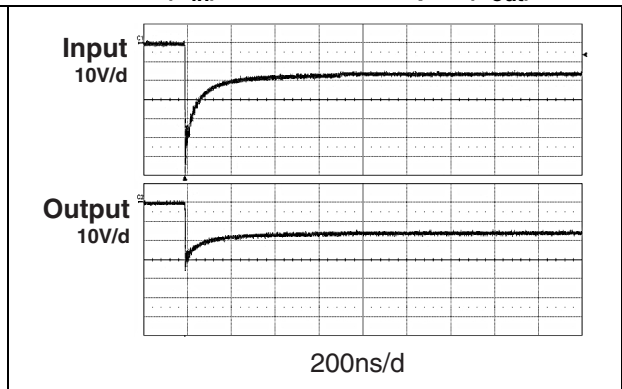
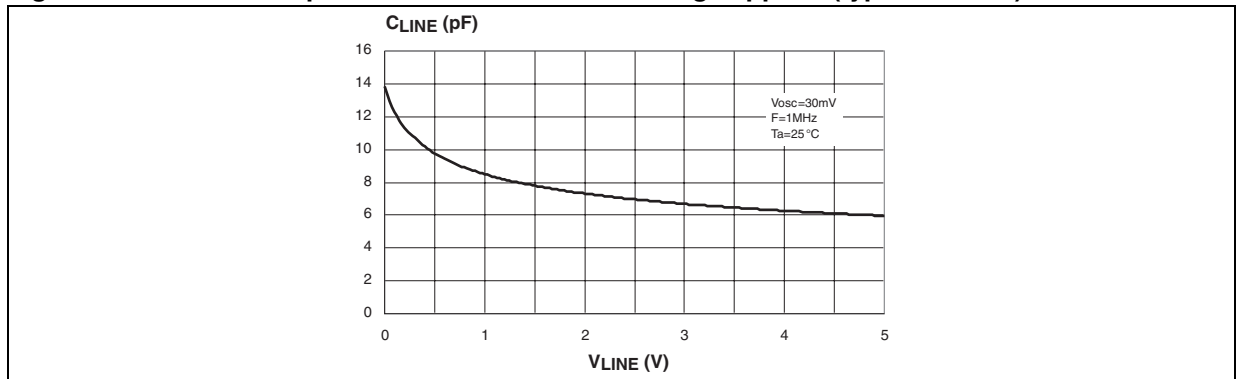


Figure 7. Junction capacitance versus reverse voltage applied (typical values)



2 Application information

Figure 8. Aplac model device structure

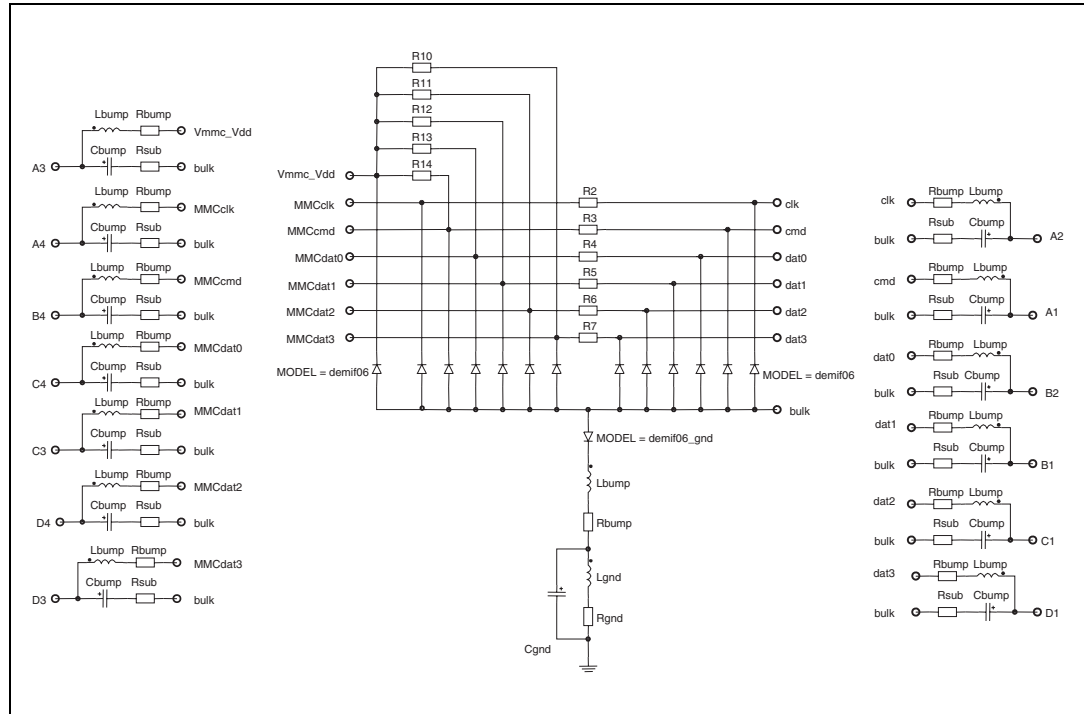
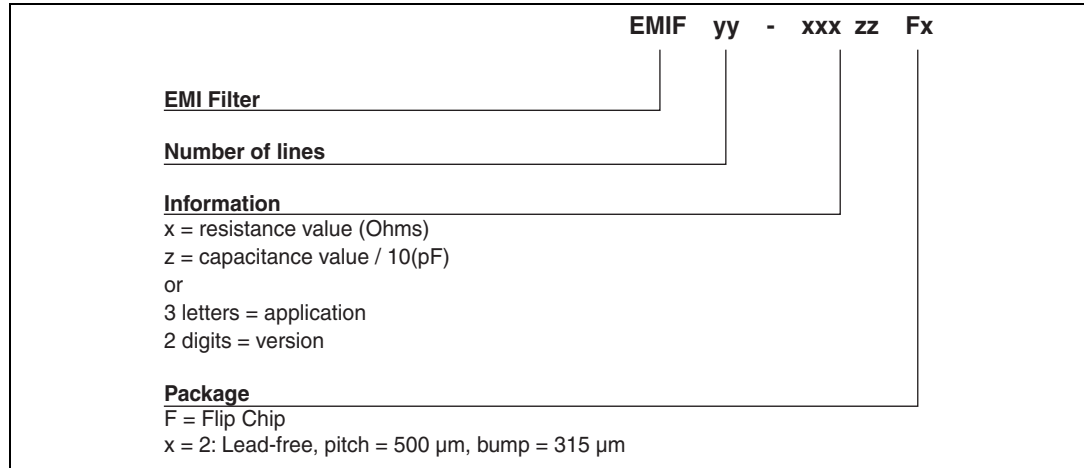


Figure 9. Aplac parameters

Variables	Variables	demif06_gnd	demif06
R2 50	Cz 11pF	BV=14	BV=14
R3 50	Cz_gnd 45pF	IBV=1m	IBV=1m
R4 50	RS_gnd 480m	CJO=Cz_gnd	CJO=Cz
R5 50	Ls 950pH	M=0.31	M=0.31
R6 50	Rs 150m	RS=RS_gnd	RS=1
R7 50	Rbump 100m	VJ=0.6	VJ=0.6
R10 75k	Lbump 50pH	TT=100n	TT=100n
R11 75k	Cbump 0.15pF		
R12 75k	Lgnd 50pH		
R13 75k	Rgnd 100m		
R14 7k	Cgnd 0.15pF		
Rsub 100m			

3 Ordering information scheme

Figure 10. Ordering information scheme



4 Package information

In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at www.st.com.

Figure 11. Package dimensions

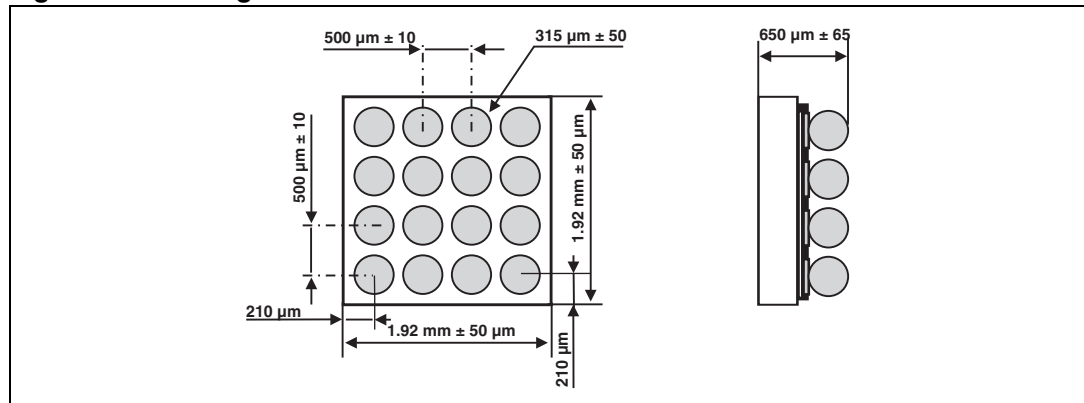


Figure 12. Footprint

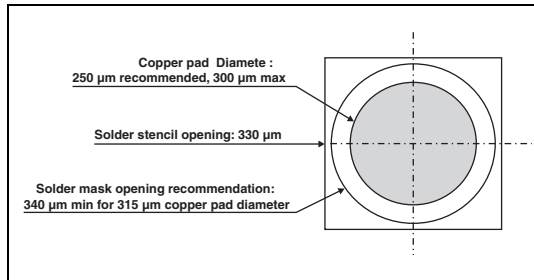


Figure 13. Marking

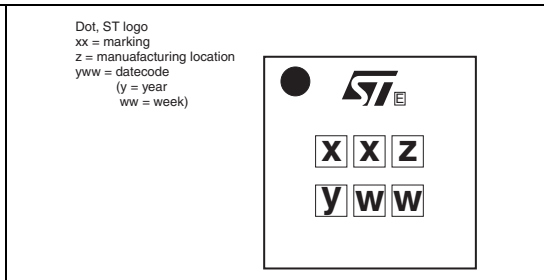
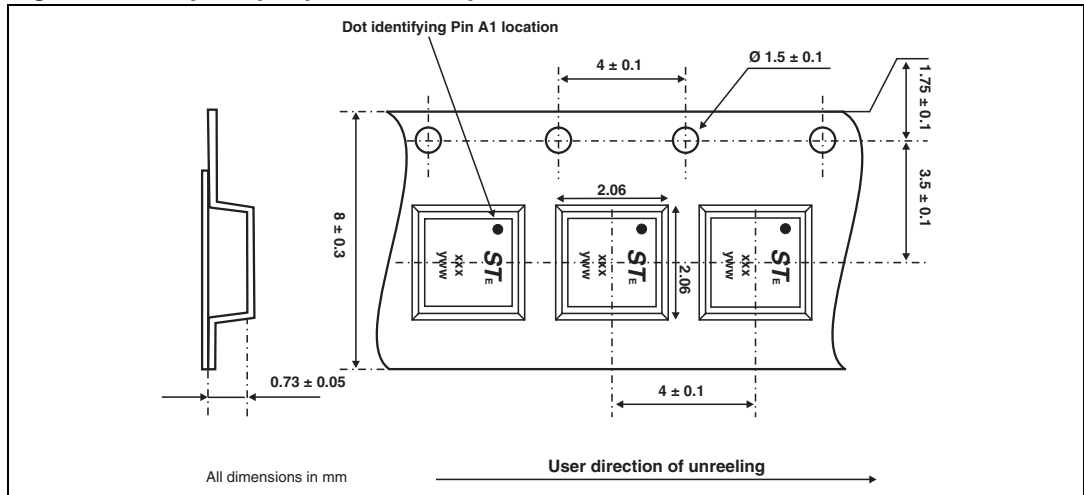


Figure 14. Flip Chip tape and reel specification



Note: More information is available in the application notes:
AN1235: "Flip Chip: Package description and recommendations for use"
AN1751: "EMI filters: Recommendations and measurements"

5 Ordering information

Table 3. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
EMIF06-HMC01F2	GH	Flip Chip	5.3 mg	5000	Tape and reel 7"

6 Revision history

Table 4. Document revision history

Date	Revision	Changes
25-Jan-2005	1	Initial release.
28-Apr-2008	2	Updated ECOPACK statement. Updated <i>Figure 10</i> , <i>Figure 11</i> , <i>Figure 12</i> , <i>Figure 13</i> and <i>Figure 14</i> . Reformatted to current standards.

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